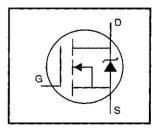
International TOR Rectifier

IRF530PbF

HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- 175°C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead-Free

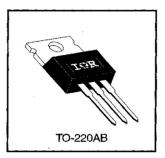


$$V_{DSS} = 100V$$
 $R_{DS(on)} = 0.16\Omega$
 $I_D = 14A$

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



Absolute Maximum Ratings

A020780 MAX TO DEA BUILD TO THE	Parameter	Max.	Units		
Ip @ Tc = 25°C	Continuous Drain Current, VGS @ 10 V	14			
In @ T _C = 100°C	Continuous Drain Current, VGS @ 10 V 10		Α		
IDM	Pulsed Drain Current ①	56			
P _D @ T _C = 25°C	Power Dissipation	88	W		
	Linear Derating Factor	0.59	W/°C		
V _{GS}	Gate-to-Source Voltage	±20	V		
Eas	Single Pulse Avalanche Energy ②	69	mJ		
I _{AR}	Avalanche Current ①	14	Α		
EAR	Repetitive Avalanche Energy ①	8.8	mJ		
dv/dt	Peak Diode Recovery dv/dt ③	5.5	V/ns		
TJ	Operating Junction and	-55 to +175			
TSTG	Storage Temperature Range		°C		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)			
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1 N•m)	1		

Thermal Resistance

	Parameter	Min.	Тур.	Max.	Units
Reuc	Junction-to-Case	—		1.7	
Recs	Case-to-Sink, Flat, Greased Surface	_	0.50		°C/W
Reja	Junction-to-Ambient			62	

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IRF530PbF

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Test Conditions	
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	100	_	_	٧	V _{GS} =0V, I _D = 250μA	
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	-	0.12	_	V/°C	Reference to 25°C, I _D = 1mA	
R _{DS(on)}	Static Drain-to-Source On-Resistance	_	_	0.16	Ω	V _{GS} =10V, I _D =8.4A ④	
V _{GS(th)}	Gate Threshold Voltage	2.0	_	4.0	V	V _{DS} =V _{GS} , I _D = 250μA	
g fs	Forward Transconductance	5.1			S	V _{DS} =50V, I _D =8.4A ④	
	Dunin to Source Lookage Current	_		25	μА	V _{DS} =100V, V _{GS} =0V	
loss	Drain-to-Source Leakage Current	_	_	250	μΑ	V _{DS} =80V, V _{GS} =0V, T _J =150°C	
I _{GSS}	Gate-to-Source Forward Leakage	_		100	nΑ	V _{GS} =20V	
IGSS	Gate-to-Source Reverse Leakage	—	_	-100	11/4	V _{GS} =-20V	
Q_g	Total Gate Charge	-	_	26		I _D =14A	
Q_{gs}	Gate-to-Source Charge	-	-	5.5	nC	V _{DS} =80V	
Q_{gd}	Gate-to-Drain ("Miller") Charge	-		11		V _{GS} =10V See Fig. 6 and 13 @	
t _{d(on)}	Turn-On Delay Time	-	10	_		V _{DD} =50V	
t _r	Rise Time	_	34	_	ns	I _D =14A	
t _{d(off)}	Turn-Off Delay Time	-	23] "13	R _G =12Ω	
t _f	Fall Time	_	24			R _D =3.6Ω See Figure 10 @	
LD	Internal Drain Inductance	_	4.5		nH	Between lead, 6 mm (0.25in.)	
Ls	Internal Source Inductance		7.5		"",	from package and center of die contact	
Ciss	Input Capacitance	_	670			V _{GS} =0V	
Coss	Output Capacitance	l –	250	_	рF	V _{DS} =25V	
Crss	Reverse Transfer Capacitance	-	60			f=1.0MHz See Figure 5	

Source-Drain Ratings and Characteristics

	Parameter	Min.	Тур.	Max.	Units	Test Conditions
ls	Continuous Source Current (Body Diode)	-	_	14	А	MOSFET symbol showing the
I _{SM}	Pulsed Source Current (Body Diode) ①		_	56		integral reverse p-n junction diode.
V _{SD}	Diode Forward Voltage		_	2.5	٧	T _J =25°C, I _S =14A, V _{GS} =0V 4
trr	Reverse Recovery Time	-	150	280	ns	T _J =25°C, I _F =14A
Qrr	Reverse Recovery Charge	_	0.85	1.7	μС	di/dt=100A/μs ④
ton	Forward Turn-On Time	Intrinsi	Intrinsic turn-on time is neglegible (turn-on is dominated by Ls+LD)			

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)
- ③ IsD≤14A, di/dt≤140A/ μ s, VDD≤V(BR)DSS, TJ≤175°C
- $^{\circ}$ V_{DD}=25V, starting T_J=25°C, L=528μH R_G=25Ω, I_{AS}=14A (See Figure 12)
- ④ Pulse width ≤ 300 μs; duty cycle ≤2%.

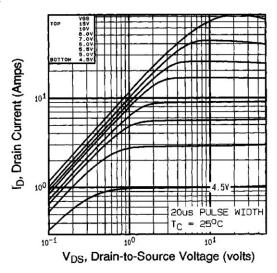


Fig 1. Typical Output Characteristics, $T_C=25^{\circ}C$

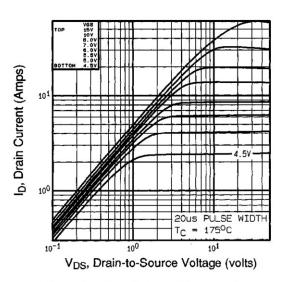


Fig 2. Typical Output Characteristics, T_C=175°C

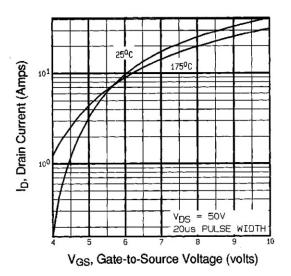


Fig 3. Typical Transfer Characteristics

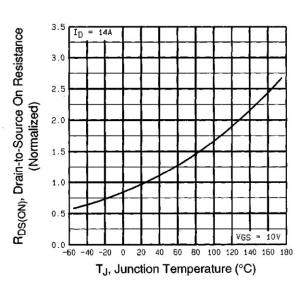


Fig 4. Normalized On-Resistance Vs. Temperature

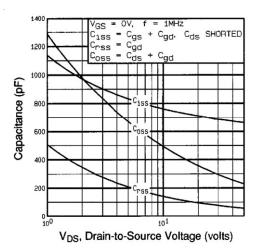


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

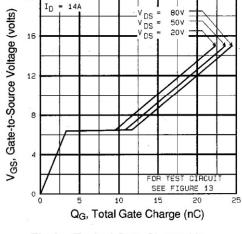


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

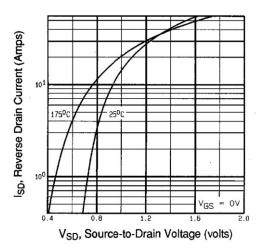


Fig 7. Typical Source-Drain Diode Forward Voltage

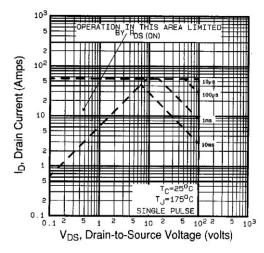


Fig 8. Maximum Safe Operating Area

IRF530PbF

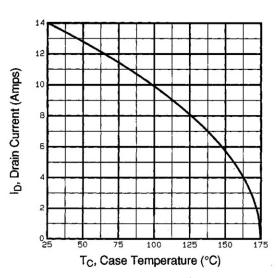


Fig 9. Maximum Drain Current Vs. Case Temperature

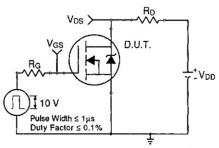


Fig 10a. Switching Time Test Circuit

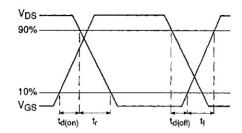


Fig 10b. Switching Time Waveforms

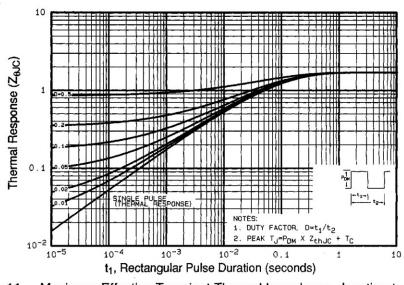


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

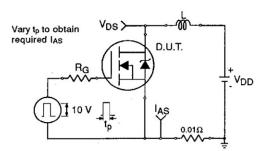


Fig 12a. Unclamped Inductive Test Circuit

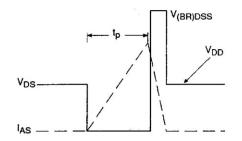


Fig 12b. Unclamped Inductive Waveforms

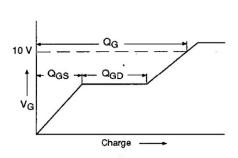


Fig 13a. Basic Gate Charge Waveform

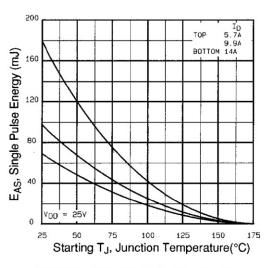


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

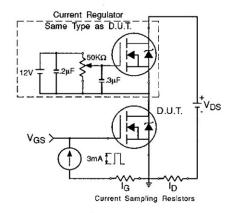


Fig 13b. Gate Charge Test Circuit

Appendix A: Figure 14, Peak Diode Recovery dv/dt Test Circuit - See page 1505

Appendix B: Package Outline Mechanical Drawing - See page 1509

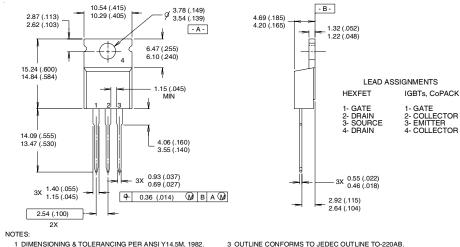
Appendix E: Optional Leadforms - See page 1525



IRF530PbF

TO-220AB Package Outline

Dimensions are shown in millimeters (inches)

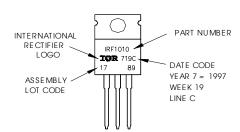


- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982

TO-220AB Part Marking Information

EXAMPLE: THIS IS AN IRF1010 LOT CODE 1789 ASSEMBLED ON WW 19, 1997 IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line position indicates "Lead-Free"



Data and specifications subject to change without notice.

International IOR Rectifier

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